19/05/06
2006033625

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
15 July 2004 (15.07.2004)

PCT

(10) International Publication Number
WO 2004/058453 A1

(51) International Patent Classification[7]: B24D 11/00

(21) International Application Number: PCT/KR2003/002831

(22) International Filing Date: 24 December 2003 (24.12.2003)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:
10-2002-0085856
28 December 2002 (28.12.2002) KR

(71) Applicant (*for all designated States except US*): SKC CO., LTD. [KR/KR]; 633 Jeongja-1-dong, Jangan-gu, Suwon, Kyungki-do 440-745 (KR).

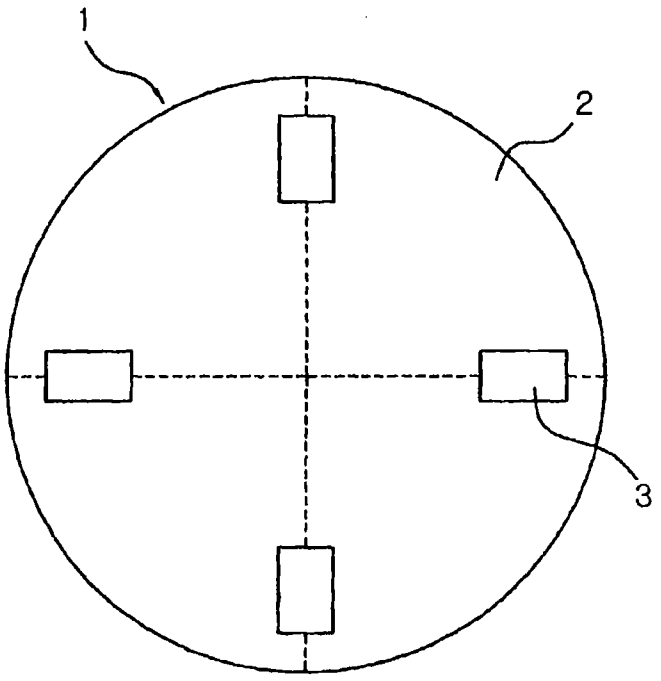
(72) Inventors; and
(75) Inventors/Applicants (*for US only*): KIM, Jae-Seok [KR/KR]; 2-506 Sampoong Apt., Seocho-4-dong, Seocho-gu, Seoul 137-779 (KR). KIM, Geon [KR/KR]; 224-101 Byucksan Apt., Youngtong-dong, Paldal-ku, Suwon, Kyungki-do 442-744 (KR). KIM, Sung-Min [KR/KR]; 106 Sansoo-ri, Booyong-myun, Chungwon-gun, Choongchungbook-do 363-941 (KR). LEE, Ju-Yeol [KR/KR]; 101-1402 Donga Apt., Jeongja-dong, Bundang-gu, Sungnam, Kyungki-do 463-010 (KR). LEE, Jong-Myung [KR/KR]; 307-403 Songgang-Green Apt., Songgang-dong, Yusong-gu, Daejeon 305-751 (KR). LEE, Hyun-Woo [KR/KR]; 766 Soogok-dong, Heungduk-gu, Cheongjoo, Choongchungbook-do 361-150 (KR). PARK, In-Ha [KR/KR]; 604-102 Mokdong Apt., 911 Mok-6-dong, Yangchun-gu, Seoul 158-056 (KR). SONG, Eu-Gene [KR/KR]; 310-19 Sachang-dong, Heungduk-gu, Cheongjoo, Choongchungbook-do 361-833 (KR).

(74) Agent: C & S PATENT AND LAW OFFICE; C-2306 Daelim Acrotel, 467-6 Dogok-dong, Kangnam-gu, Seoul 135-971 (KR).

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB,

[Continued on next page]

(54) Title: POLISHING PAD HAVING MULTI-WINDOWS



(57) Abstract: A polishing pad of the invention enables the polished quantity of a wafer to be monitored rapidly and precisely in Chemical Mechanical Polishing. A plurality of transparent windows are introduced enabling the polished quantity of the wafer to be controlled more rapidly and precisely than in a conventional single transparent window structure. The transparent windows and the remaining portion of the pad (e.g., a polishing section) are integrally made of the same material so that the polishing pad of the invention enables a precise CMP process and achieve excellent structural endurance superior to a conventional pad of a single transparent window inserted therein.

WO 2004/058453 A1

162162

ACTION